



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-06-29
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Giovanni Giacopello	Representative Title	IPD MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement

Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	88WQ*UA50BB5	A	CA2A	2015-06-29
Amount	UoM	Unit type	ST ECOPACK Grade	
17.10	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
ting is used or other bulk terminat	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	3x3x1	10	No lead	
Comment	Package: VDFPN 3x3x1.0 10 PITCH 0.50; MDF valid for L7985TR			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-17th December 2014				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	88WQ*UA508B5					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	2.072	mg	supplier	die	Silicon (Si)	7440-21-3		1.976	mg	953668	115556
				supplier	metallization	Aluminium (Al)	7429-90-5		0.020	mg	9653	1170
				supplier	metallization	Tungsten (W)	7440-33-7		0.016	mg	7722	936
				supplier	Passivation	Silicon Nitride	12033-89-5		0.004	mg	1931	234
				supplier	Passivation	Silicon Oxide	7631-86-9		0.035	mg	16892	2047
				supplier	polymer die coating	PIX1 Gamma-butyrolactone	96-48-0		0.021	mg	10135	1228
Leadframe	Copper & its alloys	10.021	mg	supplier	alloy	Copper (Cu)	7440-50-8		9.972	mg	995110	583158
				supplier	alloy	Iron (Fe)	7439-89-6		0.005	mg	499	292
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.008	mg	798	468
				supplier	metallization	Nickel (Ni)	7440-02-0		0.033	mg	3293	1930
				supplier	metallization	Palladium (Pd)	7440-05-3		0.002	mg	200	117
				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	100	58
Die attach	Other inorganic materials	0.576	mg	supplier	glue	Silver (Ag)	7440-22-4		0.394	mg	684028	23041
				supplier	glue	methylene diacrylate	42594-17-2		0.144	mg	250000	8421
				supplier	glue	Dicyclopentenyl oxethyl methacrylate	68586-19-6		0.017	mg	29514	994
				supplier	glue	Polymer of Polybutadiene + Anhydride	Proprietary		0.017	mg	29514	994
				supplier	glue	Bis(α,α-dimethylbenzyl) peroxide	80-43-3		0.003	mg	5208	175
				supplier	glue	Palladium (Pd)	7440-05-3		0.001	mg	1736	58
Bonding wires	Precious metals	0.202	mg	supplier	wire	Gold (Au)	7440-57-5		0.200	mg	990099	11696
				supplier	wire	Palladium (Pd)	7440-05-3		0.002	mg	9901	117
Encapsulation	Other Organic Materials	4.229	mg	supplier	mold compound	silica vitreous	60676-86-0		3.608	mg	853157	210994
				supplier	mold compound	epoxy resin	25068-38-6		0.169	mg	39962	9883
				supplier	mold compound	Phenol resin	29690-82-2		0.148	mg	34996	8655
				supplier	mold compound	Magnesium hydroxide	1309-42-8		0.169	mg	39962	9883
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		0.085	mg	20099	4971
				supplier	mold compound	Zinc hydroxide	20427-58-1		0.042	mg	9931	2456
				supplier	mold compound	carbon black	1333-86-4		0.008	mg	1892	468